

# Alltemated Press Release

ALLTEMATED INC.

6/9/2015

## *On the Increase*

### Alltemated's Expansion

Fast-paced programming, tape and reel, and assembly servicing company Alltemated Inc. is expanding their capacity at their Arlington Heights, IL facility. With additional staff and the implementation of new equipment, Alltemated is

marking and laser-ablation. They have also purchased additional taping machines and IC programming equipment. As the market continues to change, the company is growing systematically with the trends. With more

satisfying the demands of current and inquiring customers. Alltemated is now equipped with three lasers for mass production of PLACE-N-BOND™ underfilms and other services such as laser cut parts, component laser-

equipment, staff, and now a new product, 2015 is turning into quite a year for Alltemated.

## *Place N Bond™*

### New Versions Announced

In early May of 2015, Alltemated announced they will be offering new versions of their original PLACE-N-BOND™ products with adhesive dots pre-applied to the strip as an alternative for "tacky-pads."

The original RP-113178 series now has new versions RP-113178-A-1 and RP-113178-A-2 with this inventive pre-applied adhesive solution. Testing is even more attractive as it seamlessly integrates into a

## *Alltemated Inc.*



Alltemated Inc. was established in 1993. Our goal is to provide inventive engineering, excellent customer service, and a one-stop shop for all your assembly and servicing needs.

We offer custom design, tape and reel, programming of IC's, hard drive cloning, complete assembly, and diversified manufacturing.

Our motto is "When you need a solution, don't get frustrated. Get ALLTEMATED."

### **Contact:**

Alltemated Inc.  
3353 N Ridge Ave.  
Arlington Heights, IL 60004  
(847) 394-5800  
Email: [info@alltemated.com](mailto:info@alltemated.com)  
Web: [Alltemated.com](http://Alltemated.com)

standard SMT feeder and saves the time and expense of having to modify circuit boards to accommodate PLACE-N-BOND™ during trials.

Alltemated's engineering team has also been working hard to broaden PLACE-N-BOND's™ capabilities to help solder joints on LGAs. A thinner version of underfilm successfully helped improve LGAs during shock, drop, and thermal cycling testing. This new version of PLACE-N-BOND™ creates the opportunity to add strength in an area where underfill has had difficulties.